



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

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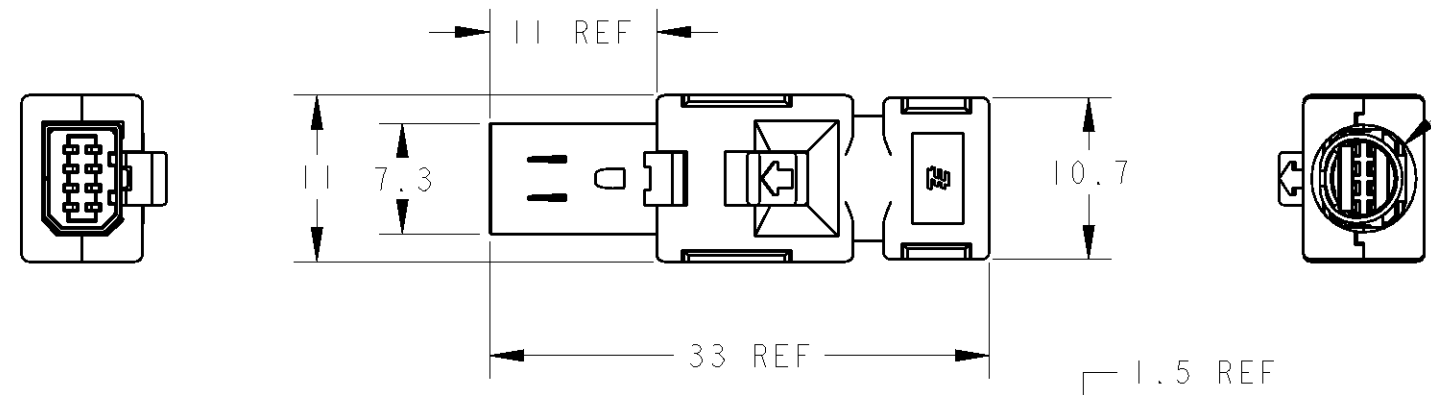
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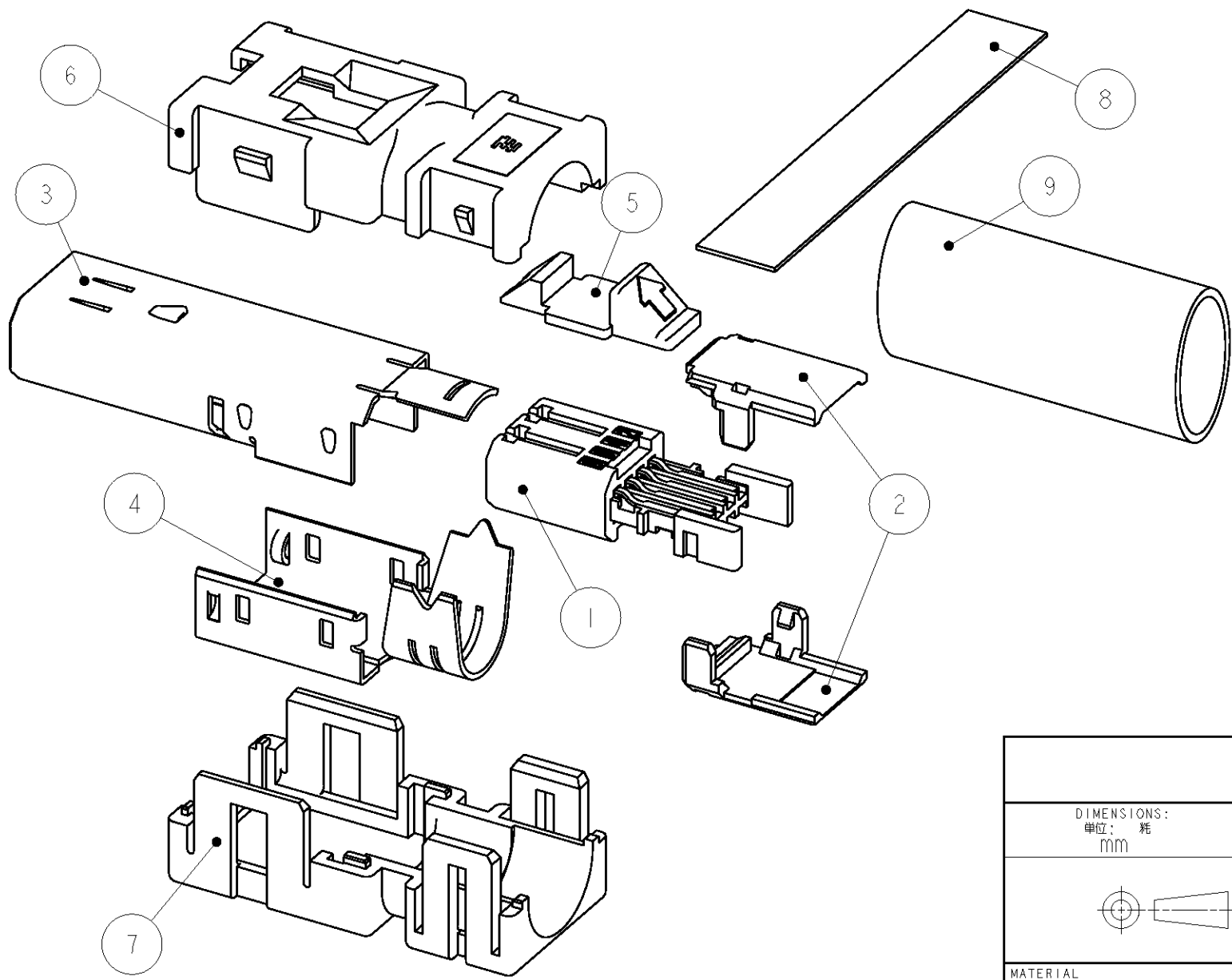
LOC	DIST	REVISIONS					
J	-	P	LTR	DESCRIPTION	DATE	DWN	APVD
		C1		REVISED PER ECO-11-005030	26APR11	RK	HMR



注記  
 1. 適合電線：導体サイズAWG22 MAX. 8芯 MAX. 仕上がり外径φ6.7 MAX.  
 2. テートコードは同梱の顧客図面に記載。  
 3. 本型番の製品は専用梱包トレーに1SETずつ個別梱包される。

NOTE  
 1. APPLICABLE CABLE: 22AWG MAX×8C MAX, OVERALL DIAMETER 6.7MAX.  
 2. DATE CODE IS DESCRIBED ON THE BUNDLED CUSTOMER DRAWING.  
 3. THE PRODUCT OF THIS DRAWING NO. IS PACKED INDIVIDUALLY IN PACKAGE OF EXCLUSIVE USE.

D-SHAPE TYPE I  
 回路番号  
 CIRCUIT NO.



-	1	1	CROSS-LINKED POLYOLEFIN 架橋ポリオレフィン	HEAT SHRINKABLE TUBE 熱収縮チューブ	⑨
-	1	1	ELECTROLYSIS COPPER FOIL, ACRYLIC ADHESIVE MATERIAL 電解銅箔 アクリル系粘着材	COPPER FOIL TAPE 銅箔テープ	⑧
1	-	-	POLYESTER OF GLASS FILLED THERMO PLASTIC(UL94V-0) ガラス入りポリエステル系熱可塑性樹脂(UL94V-0)	BOTTOM COVER ボトムカバー 色: 灰色	⑦
-	1	1	POLYESTER OF GLASS FILLED THERMO PLASTIC(UL94V-0) ガラス入りポリエステル系熱可塑性樹脂(UL94V-0)	BOTTOM COVER ボトムカバー 色: 黒	⑥
1	-	-	POLYESTER OF GLASS FILLED THERMO PLASTIC(UL94V-0) ガラス入りポリエステル系熱可塑性樹脂(UL94V-0)	TOP COVER トップカバー 色: 灰色	⑤
-	1	1	POLYESTER OF GLASS FILLED THERMO PLASTIC(UL94V-0) ガラス入りポリエステル系熱可塑性樹脂(UL94V-0)	TOP COVER トップカバー 色: 黒	④
-	1	-	POLYESTER OF GLASS FILLED THERMO PLASTIC(UL94V-0) ガラス入りポリエステル系熱可塑性樹脂(UL94V-0)	LOCK EJECTOR ロックエジェクタ 矢印白	③
1	-	1	POLYESTER OF GLASS FILLED THERMO PLASTIC(UL94V-0) ガラス入りポリエステル系熱可塑性樹脂(UL94V-0)	LOCK EJECTOR ロックエジェクタ	②
1	1	1	STEEL/UNDER: Cu PLATING, TOP: Ni PLATING 鋼/下地: Cuめっき, 表面: Niめっき	BOTTOM SHELL ボトムシェル	①
1	1	1	STEEL/UNDER: Cu PLATING, TOP: Ni PLATING 鋼/下地: Cuめっき, 表面: Niめっき	TOP SHELL トップシェル	
2	2	2	POLYESTER OF GLASS FILLED THERMO PLASTIC(UL94V-0) ガラス入りポリエステル系熱可塑性樹脂(UL94V-0)	PLUG HSG COVER プラグハウジングカバー	
1	1	1	CONTACT: COPPER ALLOY UNDER ALL SURFACE: Ni PLATING 1.27μmMIN TOP CONTACT AREA: Au PLATING: 0.5μmMIN SOLDERING AREA: Au FLASH HSG: POLY-AMID OF GLASS FILLED THERMO PLASTIC(UL94V-0) CONTACT: 銅合金 下地: 全面Niめっき1.27μm以上 表面: 接点部Auめっき0.5μm以上 はんだ付け部Auフラッシュめっき ハウジング: ガラス入りポリアミド系熱可塑性樹脂(UL94V-0)	PLUG HSG SUB ASSY プラグハウジングサブアセンブリ	
2013595-3	2013595-2	2013595-1			
REQ'D/ASSY 員数	MATERIAL / FINISH 材料 / 仕上げ			PART NAME 部品名称	ITEM NO.

DIMENSIONS: 単位: 概 mm		TOLERANCES UNLESS OTHERWISE SPECIFIED: 一般公差 ±0.3 ① PLC ± ② PLC ±0.5 ③ PLC ±0.13 ④ PLC ±0.013 ⑤ PLC ±0.0001 ANGLES ±		DWN S. INOMATA 12NOV2007 CHK L. HASEGAWA 12NOV2007 APVD L. HASEGAWA 12NOV2007 PRODUCT SPEC 108-78405 APPLICATION SPEC 114-5431 WEIGHT -			
MATERIAL 材料 SEE TABLE 表参照		FINISH 仕上 SEE TABLE 表参照		NAME 名称 INDUSTRIAL MINI I/O PLUG CONNECTOR KIT D-SHAPE TYPE I		RESTRICTED TO	
CUSTOMER DRAWING		SCALE 尺度 NON		SIZE A300779		DRAWING NO 番号 C-2013595	
				SHEET OF 1		REV C1	